



Date: May 5, 2020

RE: RE: Migration to Lead Free FPGA Flip Chip Products Pursuant to PDN2009

Dear Valued Intel Customer:

This letter is to inform you that Intel received notification from its supply chain that eutectic leaded bumped die supply will be discontinued. There is foreseen shift in demand towards lead free bumping with the EU Restriction of Hazardous Substances (RoHS) Directive Exemption15 expiry in July 21, 2021.

For supply chain continuity, Intel advised customers through *ADV2001 Rev 1.1.0* on April 3, 2020 and *PDN2009* on March 30, 2020 to migrate from Field Programmable Gate Array (FPGA) Flip Chip products that currently use leaded solder bumps on the 1<sup>st</sup> level interconnect and leaded solder balls as 2<sup>nd</sup> level interconnect (Ordering Part Numbers (OPN) with RoHS compliance suffix omitted) to FPGA Flip Chip products with lead free solder bumps and lead free solder balls (OPN with the "G" suffix). As stated in *PDN2009*, the affected leaded OPNs will be discontinued. At this time, we do not expect any significant material cost differences between the OPN's with "G" suffix and the equivalent leaded OPN.

For customers requiring FPGA Flip Chip products with lead free solder bumps and leaded solder balls (OPN with the "P" suffix), please contact your Intel sales representative or channel partner for more details on business eligibility and applicable terms & conditions. The material cost of the OPN's with "P" suffix is higher than the equivalent OPN's with "G" suffix due to increased development and manufacturing costs.

We appreciate your business and are committed to supply chain continuity of products listed above. Please contact your Intel sales representative or channel partner for questions or to place an order for samples.

Sincerely,

A handwritten signature in black ink, appearing to read "Raj Patel".

Raj Patel

Director, FPGA Product Marketing  
Intel Corporation